

Workshop SCAPE 2019

13-14 May 2019, Radisson Blu Royal Park Hotell



Tuesday 14 May

08:30 - 09:00 Registration & coffee

GaN Devices & Modules

09:00 **Thierry Bouchet, Leti**
A new 650V GaN Half Bridge Power IC to Reach Ultimate USB Power Delivery Efficiency

09:20 **Marco Panizza, Panasonic**
TBD

09:40 **Mattia Guacci, ETH**
Analysis of Monolithic Bidirectional GaN-switches and a New Modulation Scheme for Three-phase CSIs

10:00 - 10:30 Coffee & Exhibition

Resonant Convertors

10:30 **Enrique Dede, Smart Induction Converter Technologies**
SiC Ultra Compact Smart Inverter Module for Induction Heating Applications

10:50 **John Kåre Langelid, EFD Induction**
Practical Experiences Using SiC DioMos in High Frequency High Power Series Resonant Applications

11:10 **Per Ranstad, KTH, Royal Institute of Technology**
TBD

Modeling

11:30 **Andreas Huerner, Infineon**
Compact-Models for SiC-MOSFETs

11:50 - 13:10 Lunch & Exhibition

Market & Roadmap

13:10 **Hong Lin, Yole Développement**
GaN & SiC power devices - Market overview

Packaging

13:40 **Kirill Klein, Fraunhofer IZM**
The Evolution of Low Inductive Power Modules

14:00 **TBD**
TBD

14:20 **Amine Allouche, System Plus Consulting**
TBD

Panel Discussion

14:40 **Chair: Hong Lin, Yole Développement**
Do we move towards wafer manufacturing integration?

Closing Remarks

15:40 **Hans-Peter Nee, KTH, Royal Institute of Technology**

16:00 **End of workshop**
